



Material Content Data Sheet



Sales Product Name		TLD5045EJ		Issued		25. September 2017		
MA#		MA000982358						
Package		PG-DSO-8-27		Weight*		84.03 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.904	2.27	2.27	22655	22655
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		433	
	non noble metal	iron	7439-89-6	0.728	0.87		8660	
wire	non noble metal	copper	7440-50-8	29.548	35.16	36.08	351640	360841
	noble metal	gold	7440-57-5	0.191	0.23	0.23	2274	2274
encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1180	
	plastics	epoxy resin	-	4.561	5.43		54274	
	inorganic material	silicondioxide	60676-86-0	44.912	53.45	59.00	534485	589939
leadfinish	non noble metal	tin	7440-31-5	0.695	0.83	0.83	8272	8272
plating	noble metal	silver	7440-22-4	0.725	0.86	0.86	8622	8622
glue	plastics	epoxy resin	-	0.155	0.18		1849	
	noble metal	silver	7440-22-4	0.466	0.55	0.73	5548	7397
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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